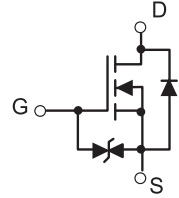
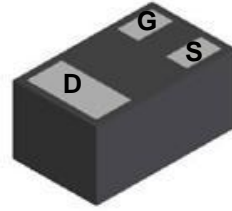




## N-Channel 20V,1.2A, N-MOSFET

### FEATURES

- TrenchFET® Power MOSFET: 1.8-V Rated
- Gate-Source ESD Protected
- High-Side Switching
- Low On-Resistance: 0.4Ω(max)
- Low Threshold: 0.7V (typ)
- Fast Switching Speed: 10 ns
- S- Prefix for Automotive and Other Applications Requiring



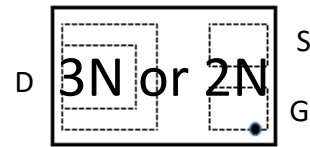
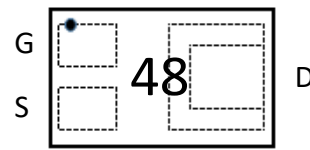
DFN1006-3L

### BENEFITS

- Ease in Driving Switches
- Low Offset (Error) Voltage
- Low-Voltage Operation
- High-Speed Circuits
- Low Battery Voltage Operation

### APPLICATIONS

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pagers



Marking: 48, 3N, 2N

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C UNLESS OTHERWISE NOTED)					
Parameter	Symbol	5 secs	Steady State	Unit	
Drain-Source Voltage	V <sub>DS</sub>	20		V	
Gate-Source Voltage	V <sub>GS</sub>	±8			
Continuous Drain Current (T <sub>J</sub> = 150°C) <sup>b</sup>	I <sub>D</sub>	T <sub>A</sub> = 25°C	1200	900	mA
		T <sub>A</sub> = 85°C	800	600	
Pulsed Drain Current <sup>a</sup>	I <sub>DM</sub>	2500			
Continuous Source Current (diode conduction) <sup>b</sup>	I <sub>S</sub>	275	250		
Maximum Power Dissipation <sup>b</sup> for SC-89	P <sub>D</sub>	T <sub>A</sub> = 25°C	275	250	mW
		T <sub>A</sub> = 85°C	160	140	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150		°C	

#### Notes

- d. Pulse width limited by maximum junction temperature.
- e. Surface Mounted on FR4 Board.



● **Electrical Characteristics (@TA=25°C unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	20	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=16V, V_{GS}=0V$	--	--	1	$\mu A$
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	0.5	--	1.0	V
Gate Leakage Current	$I_{GSS}$	$V_{GS}=\pm 8V, V_{DS}=0V$	--	--	$\pm 10$	$\mu A$
Drain-Source On-state Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=0.5A$	--	250	400	m $\Omega$
		$V_{GS}=2.5V, I_D=0.5A$	--	300	500	m $\Omega$
		$V_{GS}=1.8V, I_D=0.35A$	--	400	650	m $\Omega$
Total Gate Charge	$Q_g$	$V_{GS}=4.5V, V_{DS}=10V, I_D=1A$	--	2	--	nC
Gate- Source Charge	$Q_{gs}$		--	0.3	--	nC
Gate- Drain Charge	$Q_{gd}$		--	0.3	--	nC
Turn-on Delay Time	$t_{d(on)}$	$V_{GS}=4.5V, V_{DS}=10V, R_{GEN}=6\Omega, I_D=2A$	--	1.2	--	ns
Turn-on Rise Time	$t_r$		--	25	--	ns
Turn-off Delay Time	$t_{d(off)}$		--	14	--	ns
Turn-off Fall Time	$t_f$		--	15	--	ns
Input Capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=10V, f=1MHz$	--	43	--	pF
Output Capacitance	$C_{oss}$		--	9	--	pF
Reverse Transfer Capacitance	$C_{rss}$		--	6	--	pF

● **Reverse Diode Characteristics (@TA=25°C unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Continuous Diode Forward Current	$I_{SD}$	$V_G=V_D=0V$ , Force Current	--	--	3.5	A
Diode Forward Voltage	$V_{SD}$	$I_{SD}=0.5A, V_{GS}=0V$	--	--	1.3	V
Reverse Recovery Time	$t_{rr}$	$I_F = 1A$ $di/dt = 100 A/\mu s$	--	9	--	nS
Reverse Recovery Charge	$Q_{rr}$		--	1	--	nC

A: The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with TA=25C. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature .

C: The current rating is based on the t<10s junction to ambient thermal resistance rating.



### ● TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

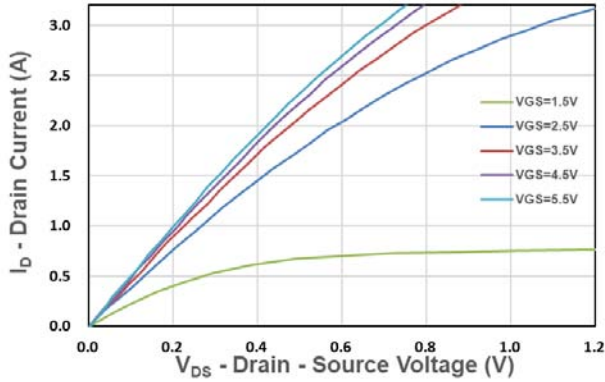


Figure 1. Output Characteristics

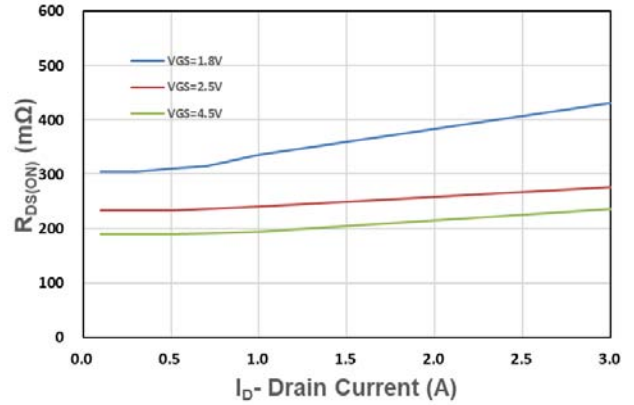


Figure 2. On-Resistance vs. I

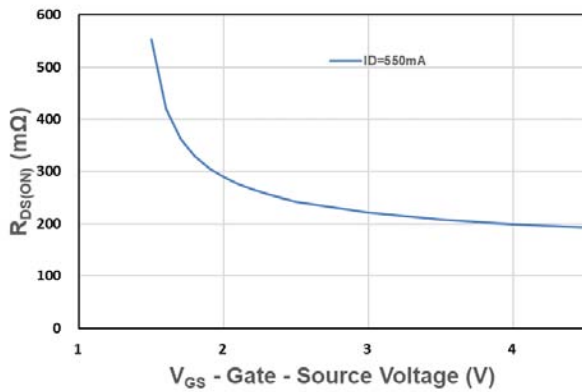


Figure 3. On-Resistance vs.  $V_{GS}$

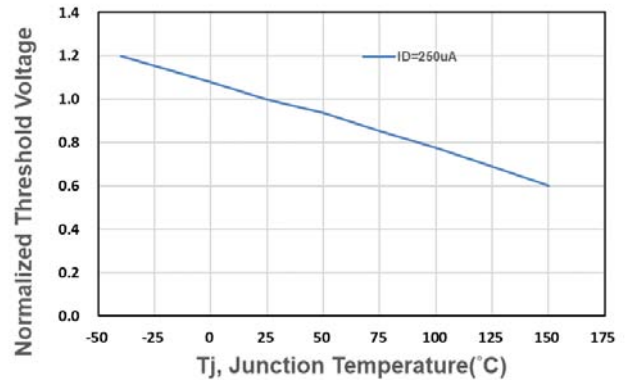


Figure 4. Gate Threshold Voltage

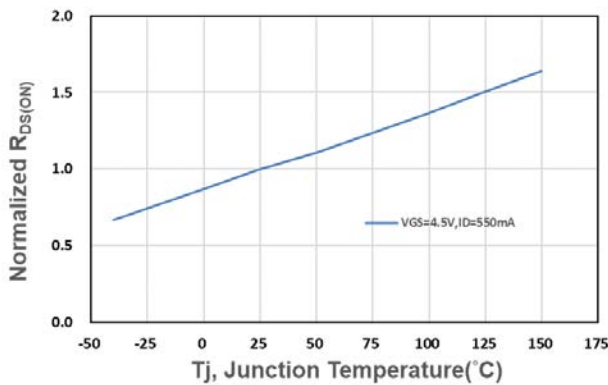


Figure 5. Drain-Source On Resistance

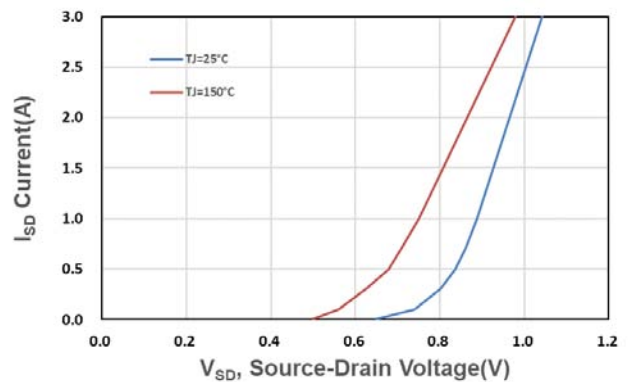


Figure 6. Source-Drain Diode Forward

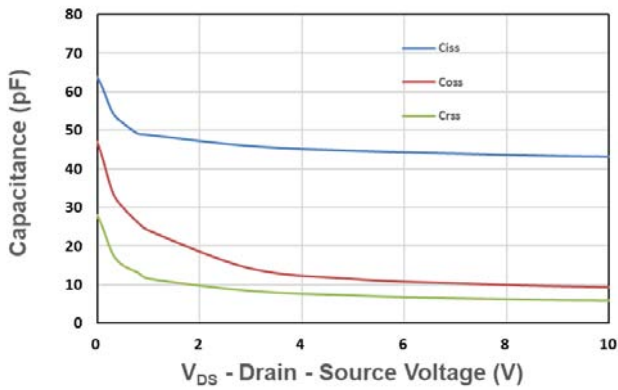


Figure 7. Capacitance

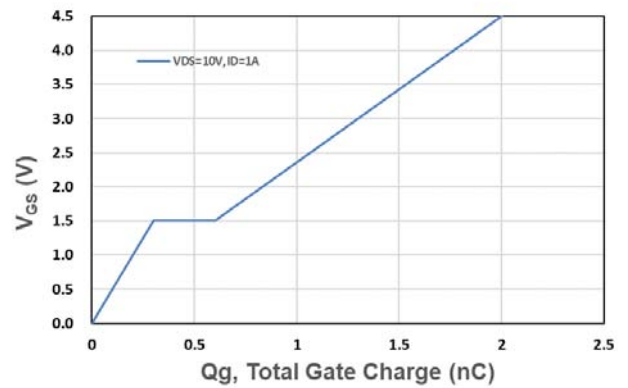


Figure 8. Gate Charge Characteristics

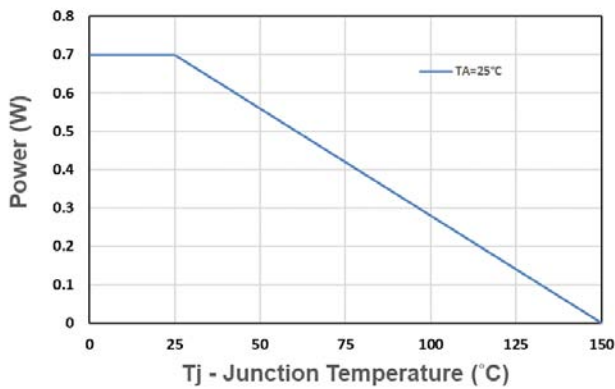


Figure 9. Power Dissipation

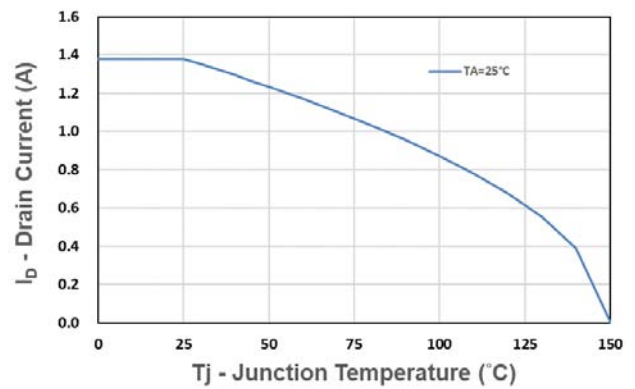


Figure 10. Drain Current

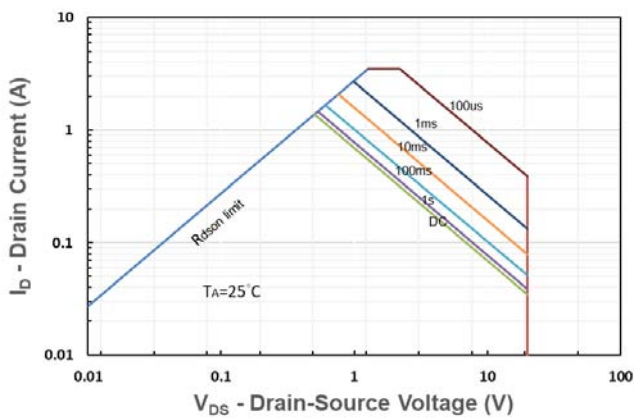


Figure 11. Safe Operating Area

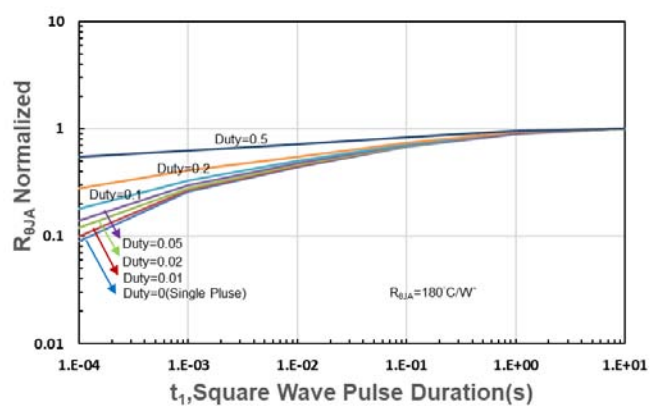


Figure 12.  $R_{\theta JA}$  Transient Thermal Impedance

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**DFN1006-3L Package Outline Dimensions**

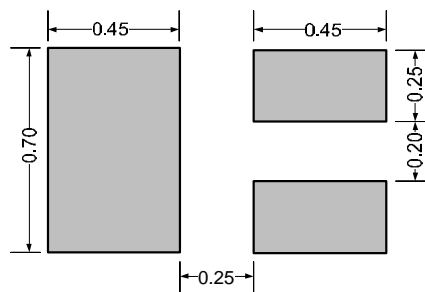
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**DFN1006-3L Suggested Pad Layout**

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**Recommend land pattern (Unit: mm)**



*Note: This land pattern is for your reference only. Actual pad layouts may vary depending on application.*

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